

HVM16

Variable Capacitance Diode for FM tuner

REJ03G0519-0600
(Previous: ADE-208-086E)
Rev.6.00
Feb 17, 2005

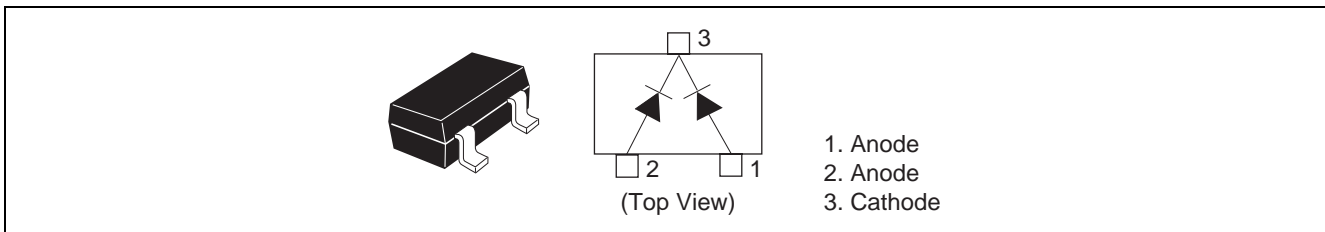
Features

- Worked by 8V, suitable for small manufacture sources of electric power.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Renesas Code	Previous Code
HVM16	T3	PLSP0003ZC-A	MPAK

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	14	V
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Electrical Characteristics *

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse voltage	V _R	14.0	—	—	V	I _R = 10 μA
Reverse current	I _R	—	—	50.0	nA	V _R = 9 V
Capacitance	C ₂	43.0	—	48.1	pF	V _R = 2 V, f = 1 MHz
	C ₈	24.6	—	29.2		V _R = 8 V, f = 1 MHz
Capacitance ratio	n	1.65	—	1.75	—	C ₂ /C ₈
Figure of merit	Q	75.0	—	—	—	V _R = 2 V, f = 100 MHz

Note: Per one device.

Main Characteristic

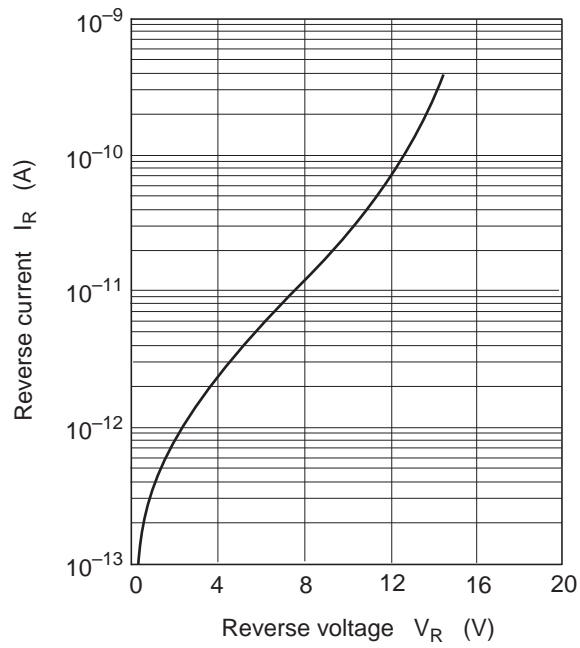


Fig.1 Reverse current vs. Reverse voltage

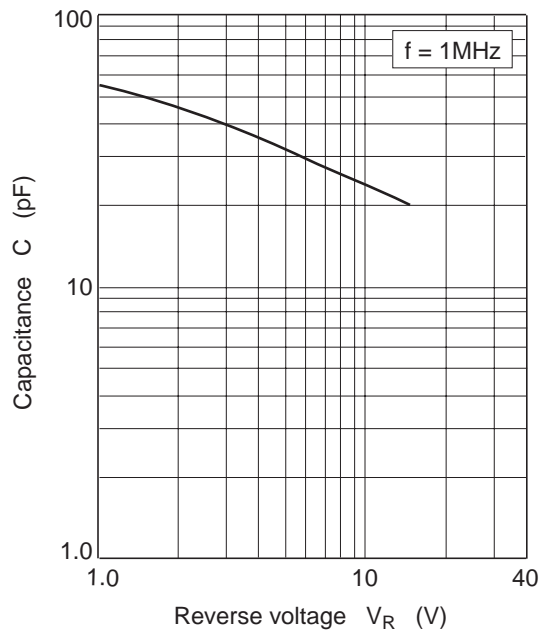
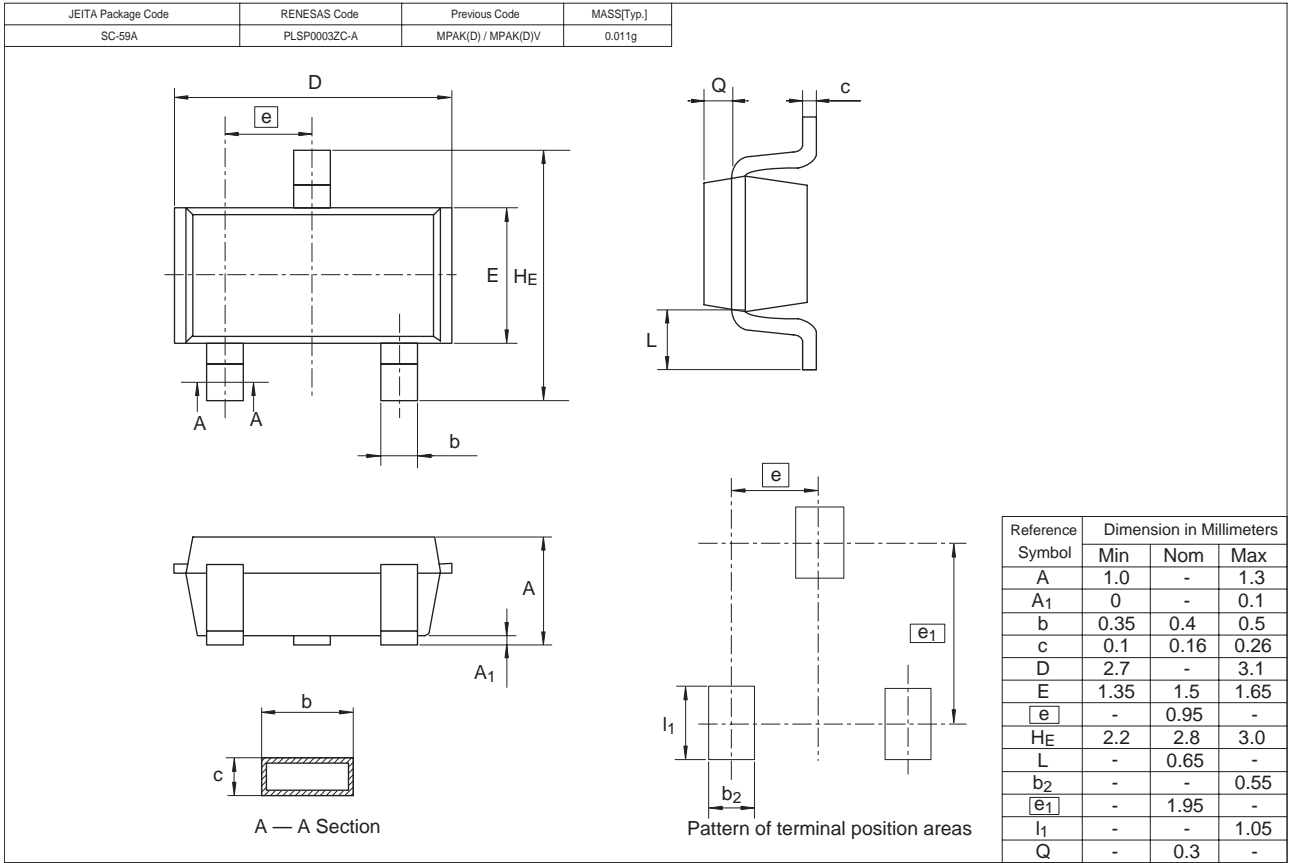


Fig.2 Capacitance vs. Reverse voltage

Package Dimensions



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